PCN Number:	20250131002.2B	PCN Date:	October 16, 2025
Title:	Adding KL-PR & TIEM-PR as additional wafer probe site		
Customer Contact:	Change Management team	Dept:	Quality Services
Proposed 1st Ship Date:	April 14, 2026	Estimated Sample Availability:	Samples not supported

Change Type:

☐	Assembly Site	☐	Design	☐	Wafer Bump Material
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Process
☐	Assembly Materials	☐	Part number change	☐	Wafer Fab Site
☐	Mechanical Specification	☒	Test Site	☐	Wafer Fab Material
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Process

PCN Details

Description of Change:

Revision B is to remove devices listed in the Product Affected Section. These devices were inadvertently added and are not affected by this change & will be probe tested at current probe sites.

Texas Instruments Incorporated has qualified KL-PR & TIEM-PR as additional probe site for the devices listed below to support high volume ramps.

	Current:	Additional:
Probe Site	CD-PR, CLARK-PR, DL-MOS-4	*TI Malaysia (KL-PR), TI Melaka (TIEM-PR)*

Test coverage, insertions, conditions will remain consistent with current testing.

Reason for Change:

Supply continuity.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings:

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

None

Product Affected:

DS90UB936TRGZRQ1	DS90UB635TRHBTQ1	DS90UB638TRGZTQ1
DS90UB954TRGZTQ1	DS90UB953ATRHBRQ1	DS90UB951TRHBRQ1
DS90UB954TRGZRQ1	DS90UB936TRGZTQ1	DS90UB638TRGZRQ1
DS90UB951TRHBTQ1	DS90UB935TRHBTQ1	DS90UB953ATRHBTQ1
DS90UB953TRHBRQ1	DS90UB953TRHBTQ1	DS90UB958TRGZTQ1
DS90UB935TRHBRQ1	DS90UB635TRHBRQ1	DS90UB958TRGZRQ1

ZVEI ID: SEM-TF-01

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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